

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Masaru SHIRAI et al. Confirmation No. 1550
Appl. No.: 10/598,142 Examiner: D'ANIELLO, N.
Filed: August 18, 2006 Group Art Unit: 1725

For: HEATER, REFLOW APPARATUS, AND SOLDER BUMP FORMING METHOD
AND APPARATUS
COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop Issue Fee
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

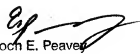
In response to the Notice of Allowability, mailed by the U.S. Patent and Trademark Office on August 8, 2011 and to the Statement of Reasons for Allowance attached thereto, Applicants wish to clarify the record with respect to the basis for the patentability of claims in the present application. In this regard, while Applicants do not disagree with the Examiner's indication of allowability, Applicants submit that each of the claims in the present application recites a combination of features, and that the basis for patentability of each of these claims is based on the combination of features recited therein.

Should there be any questions, the Examiner is invited to contact the undersigned at the below-listed telephone number.

August 26, 2011
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Respectfully submitted,
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